

60 V 100 mA Ultra-low Power Voltage Regulator

No. EA-395-190606

OVERVIEW

The R1560x is a CMOS-based ultra-low power voltage regulator featuring 60 V input voltage and 100 mA output current. The device includes a short current limit circuit, an overcurrent protection circuit and a thermal shutdown. These features make the R1560x an ideal constant voltage power source for electrical appliances.

KEY BENEFITS

- Supply current is as low as Typ. 3.0 μA, which can reduce current consumption at a system stop.
- The input voltage range is as wide as 5.5 V to 60 V, and the output voltage accuracy is as high as ±0.8%.
- High heat dissipation and space-saving HSOP-6J and TO-252-5-P2 packages.

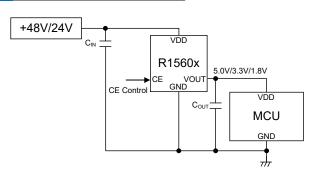
KEY SPECIFICATIONS

- Input Voltage Range (Max. Rating): 5.5 V to 60 V (80 V)
- Operating Temperature Range: -40°C to 105°C
- Supply Current: Typ. 3.0 µA
- Dropout Voltage: Typ. 1.5 V

(I_{OUT} = 100 mA, V_{OUT} = 5.0 V)

- Output Voltage Accuracy: ±0.8% (Ta = 25°C)
- Temp. Coefficient of Output Voltage: Typ. ±100 ppm/°C
- Line Regulation: Typ. 0.01%/V (6 V \leq V_{IN} \leq 60 V)
- Short-circuit Current Limiting: limits to Typ. 50 mA
- Overcurrent Protection: triggers at Typ. 150 mA
- Thermal Shutdown: triggers at Typ.165°C

TYPICAL APPLICATIONS

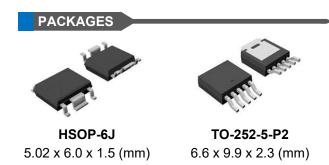


SELECTION GUIDE

Product Name	Package
R1560Sxx1B-E2-FE	HSOP-6J
R1560Jxx1B-T1-FE	TO-252-5-P2

xx: Set Output Voltage (VSET)

1.8 V (18) / 2.5 V (25) / 2.8 V (28) / 3.0 V (30) / 3.3 V (33) / 3.4 V (34) / 5.0 V (50) / 7.0 V (70) / 8.0 V (80) / 9.0 V (90) / 10.0 V (A0) / 12.0 V (C0) / 14.0 V (E0)



APPLICATIONS

- Refrigerators, Rice Cookers and Electric Kettles
- Laptop PCs, Digital TVs, Telephones and Home LAN System

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SELECTION GUIDE

The output voltage and the package type are user-selectable options.

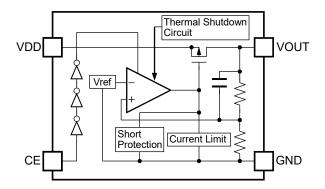
Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1560Sxx1B-E2-FE	HSOP-6J	1,000 pcs	Yes	Yes
R1560Jxx1B-T1-FE	TO-252-5-P2	3,000 pcs	Yes	Yes

xx: Set Output Voltage (VSET)

1.8 V (18) / 2.5 V (25) / 2.8 V (28) / 3.0 V (30) / 3.3 V (33) / 3.4 V (34) / 5.0 V (50) / 7.0 V (70) / 8.0 V (80) / 9.0 V (90) / 10.0 V (A0) / 12.0 V (C0) / 14.0 V (E0)

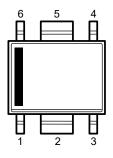
BLOCK DIAGRAM



R1560x Block Diagram

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PIN DESCRIPTIONS



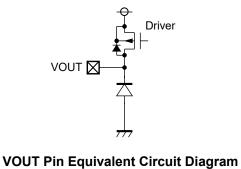
HSOP-6J Pin Configuration

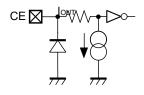
HSOP-6J Pin Desc	ISOP-6J Pin Description						
Pin No.	Pin Name	Description					
1	VOUT	Output Pin					
2	GND ⁽¹⁾	Ground Pin					
3	CE	Chip Enable Pin, Active-high					
4	GND ⁽¹⁾	Ground Pin					
5	GND ⁽¹⁾	Ground Pin					
6	VDD	Input Pin					

TO-252-5-P2 Pin Description

Pin No.	Pin Name	Description
1	VDD	Input Pin
2	NC	No Connection
3	GND	Ground Pin
4	VOUT	Output Pin
5	CE	Chip Enable Pin, Active-high

Pin Equivalent Circuit Diagrams





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TO-252-5-P2 Pin Configuration

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CE Pin Equivalent Circuit Diagram

⁽¹⁾ The GND pins are connected to each other on the board.

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ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings

Symbol		Parameter	Rating	Unit	
VIN	Input Voltage			-0.3 to 80	V
VIN	Peak Inrush Voltage	1)		90	V
VCE	CE Pin Input Voltage	•		-0.3 to 80	V
Vout	Output Voltage		-0.3 to V _{IN} + 0.3 ≤ 80	V	
Іоит	Output Current		150	mA	
D-	Power HSOP-6J JEDEC S		JEDEC STD.51-7	2700	mW
P _D Dissipation ⁽²⁾		TO-252-5-P2 JEDEC STD.51-7		3800	TTVV
Tj	Junction Temperatur	e	-40 to 125	°C	
Tstg	Storage Temperature	e Range	-55 to 125	°C	

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

Recommended Operating Conditions

Symbol	Parameter	Rating	Unit
VIN	Input Voltage	5.5 to 60	V
Та	Operating Temperature Range	−40 to 105	°C

RECOMMENDED OPERATING CONDITONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽¹⁾ Duration: 200 ms or less

⁽²⁾ Refer to POWER DISSIPATION for detailed information.

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ELECTRICAL CHARACTERISTICS

 $C_{IN} = 0.1 \ \mu\text{F} / C_{OUT} = 0.1 \ \mu\text{F}$, unless otherwise noted.

The specifications surrounded by \square are guaranteed by design engineering at $-40^{\circ}C \le Ta \le 105^{\circ}C$.

R1560x El	ectrical Characteristics	1			1	1	(Ta =	: 25°C)
Symbol	Parameter	Test Conditions/Comments			Min.	Тур.	Max.	Unit
lss	Supply Current	V _{IN} = 14 V V _{CE} = 14 V I _{OUT} = 0 mA		V _{SET} ≤ 5.0 V		3.0	8.0	
ISS		V _{IN} = 18 V V _{CE} = 18 V I _{OUT} = 0 mA		V _{SET} > 5.0 V		3.5	12	μA
Istandby	Standby Current	V _{IN} = 60 V, V	_{CE} = 0 V			0.1	2.0	μA
		V _{SET} ≤ 5.0 V	Ta = 25°	С	×0.992		×1.008	
		V _{IN} = 14 V I _{OUT} = 1 mA	-40°C ≤	Ta ≤ 105°C	×0.985		×1.015].,
Vout	Output Voltage	V _{SET} > 5.0 V	Ta = 25°	С	×0.988		×1.012	V
		V _{IN} = 18 V I _{OUT} = 1 mA	–40°C ≤ Ta ≤ 105°C		×0.980		×1.020	1
ΔVουτ /ΔΙουτ	Load Regulation	$V_{IN} = 8 V (V_{SET} \le 5.0 V)$ $V_{IN} = V_{SET} + 3 V (V_{SET} > 5.0 V)$ $1 \text{ mA} \le I_{OUT} \le 100 \text{ mA}$			Refer to Voltage-specific Electrical Characteristics			
ΔV_{OUT}		$\begin{array}{c c} 6 \ V \leq V_{\text{IN}} \leq 60 \ V \\ I_{\text{OUT}} = 1 \ \text{mA} \end{array} \qquad \qquad V_{\text{SET}} \leq 5.0 \ V \\ \end{array}$		-0.02	0.01	0.02	%/V	
$/\Delta V_{IN}$	Line Regulation	$\begin{array}{c c} V_{\text{SET}} + 1 \ V \leq V_{\text{IN}} \leq 60 \ V \\ I_{\text{OUT}} = 1 \ \text{mA} \end{array} V_{\text{SET}} > 5.0 \ \text{V}$		V _{SET} > 5.0 V	-0.06	0.03	0.06	70/V
Vdif	Dropout Voltage	Ι _{ουτ} = 100 mA	I _{OUT} = 100 mA			Refer to Voltage-specific Electrical Characteristics		
I _{LIM}	Output Current Limit	V _{IN} = 8.0 V (V V _{IN} = V _{SET} + 3			100	150	250	mA
lsc	Short-circuit Current	$V_{IN} = 8.0 V (V_{SET} \le 5.0 V)$ $V_{IN} = V_{SET} + 3 V (V_{SET} > 5.0 V)$ $V_{OUT} = 0 V$			20	50	75	mA
VCEH	CE Input Voltage "H"	V _{IN} = 60 V			3.0		60	V
VCEL	CE Input Voltage "L"	V _{IN} = 60 V			0		0.3	V
I _{PD}	CE Pull-down Current	V _{IN} = 60 V, V _{CE} = 3 V				0.4	0.8	μA
T_{TSD}	Thermal Shutdown Temperature	Junction Temperature			150	165		°C
T _{TSR}	Thermal Shutdown Release Temperature ⁽¹⁾	Junction Tem	perature		125	135		°C

All parameters are tested under the pulse load condition (Tj \approx Ta = 25°C).

⁽¹⁾ If the VDD and CE pins are turned on at the same time when Ta > 125° C, the thermal shutdown can be activated.

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Product		V _{оυт} (V) Га = 25°			V _{о∪т} (V ≤ Та ≤) 105°C)	ΔVοι	т/ ∆І оυт	(mV)	VDIF	(V)
Name	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	Max.
R1560x181B	1.7856	1.80	1.8144	1.7730	1.80	1.8270				3.7	4.0
R1560x251B	2.4800	2.50	2.5200	2.4625	2.50	2.5375				3.0	3.6
R1560x281B	2.7776	2.80	2.8224	2.7580	2.80	2.8420				2.7	3.6
R1560x301B	2.9760	3.00	3.0240	2.9550	3.00	3.0450	-300	30	300	2.5	3.6
R1560x331B	3.2736	3.30	3.3264	3.2505	3.30	3.3495				2.2	3.0
R1560x341B	3.3728	3.40	3.4272	3.3490	3.40	3.4510				2.1	3.0
R1560x501B	4.9600	5.00	5.0400	4.9250	5.00	5.0750				1.5	3.0
R1560x701B	6.9160	7.00	7.0840	6.8600	7.00	7.1400				1.5	3.0
R1560x801B	7.9040	8.00	8.0960	7.8400	8.00	8.1600			600	1.5	3.0
R1560x901B	8.8920	9.00	9.1080	8.8200	9.00	9.1800	-600	60		1.5	3.0
R1560xA01B	9.8800	10.00	10.120	9.8000	10.0	10.200			60 600	1.5	3.0
R1560xC01B	11.856	12.00	12.144	11.760	12.0	12.240				1.5	3.0
R1560xE01B	13.832	14.00	14.168	13.720	14.0	14.280				1.5	3.0

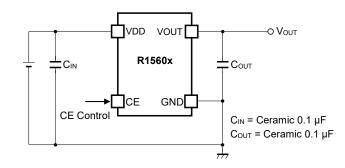
R1560x Product-specific Electrical Characteristics

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THEORY OF OPERATION

Thermal Shutdown

If the junction temperature increases above 165°C (Typ.), the operation of the regulator would stop. And if the junction temperature decreases below 135°C (Typ.), the operation of the regulator would restart. Unless the causes of temperature rising are removed, the regulator repeats turning on and off and the output waveform becomes a pulse shape.

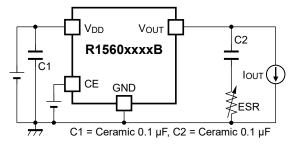


APPLICATION INFORMATION

R1560x Typical Applications

Equivalent Series Resistance vs. Output Current

It is recommended that a ceramic type capacitor be used for this device. However, other types of capacitors having lower ESR can also be used. The relation between the output current (I_{OUT}) and the ESR of output capacitor is shown below.



Measurement Conditions

Frequency Band: 10 Hz to 2 MHz Measurement Temperature: -40° C to 105° C Capacitor: C1 = Ceramic 0.1 µF, C2 = Ceramic 0.1 µF ESR: 0 to 100 Ω V_{OUT}: 1.8 V, 5.0 V It is confirmed that the output noise level is less than the specified value (40 µVrms) under the measurement conditions above.

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TECHNICAL NOTES

The performance of a power source circuit using this device is highly dependent on a peripheral circuit. A peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, please be fully aware of the following points.

Phase Compensation

A phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, use a $0.1-\mu$ F or more output capacitor (C_{OUT}) with good frequency characteristics and proper ESR (Equivalent Series Resistance). In case of using a tantalum type capacitor with a large ESR, the output might become unstable. Evaluate your circuit including consideration of frequency characteristics. Connect a $0.1-\mu$ F or more input capacitor (C_{IN}) between the VDD and GND pins with shortest-distance wiring.

PCB Layout

As for the HSOP-6J package, ensure that the GND pins (Pin No. 2, 4 and 5) are connected to each other and the ground plane.

Operating the Device below the Minimum Operating Voltage

Operating the device below the recommended operating voltage range can make the output voltage unstable and make the output voltage higher than the set output voltage (V_{SET}) of the device.

In the case of turning on the VIN and CE pins at the same time, both pins must be turned on using a 100-V/ms or more slew rate in order to prevent the unstable operation upon start-up. In the case of turning on the VIN pin using a 100-V/ms or less slew rate, the CE pin must be turned on after the supply voltage becomes 5.5 V or more.

In the case of turning off the VIN and CE pins at the same time, both pins must be turned off using a steep slew rate, -100 V/ms or higher in order to prevent the unstable operation. In the case of turning off the VIN pin using a slow rate, lower than -100 V/ms, the CE pin must be turned off before the supply voltage decreases to 5.5 V.

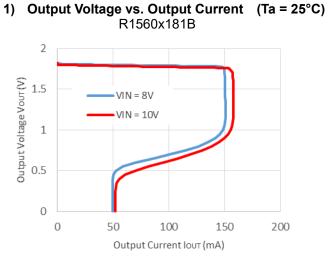
Transient Response

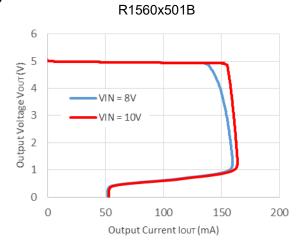
An output ceramic capacitor of $C_{OUT} = 0.1 \,\mu\text{F}$ prevents R1560x series from phase oscillation to ensure the IC's stable operation. However, variation in input voltage and load current would lead to an unstable output voltage which fails to meet the requirements of the system. Especially, in a high output version: $V_{SET} > 5 \,\text{V}$, this results in slow response of the IC and a great variation in output. To avoid this problem, use a ceramic capacitor of $C_{OUT} = 10 \,\mu\text{F}$ or more to minimize variation in output. Place the capacitor as close as possible to and outside of the IC when the electrolytic capacitor is used as an output line element.

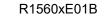
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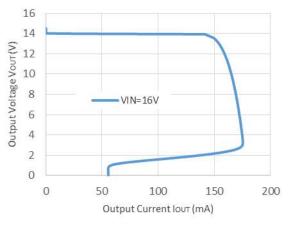
TYPICAL CHARACTERISTICS

Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

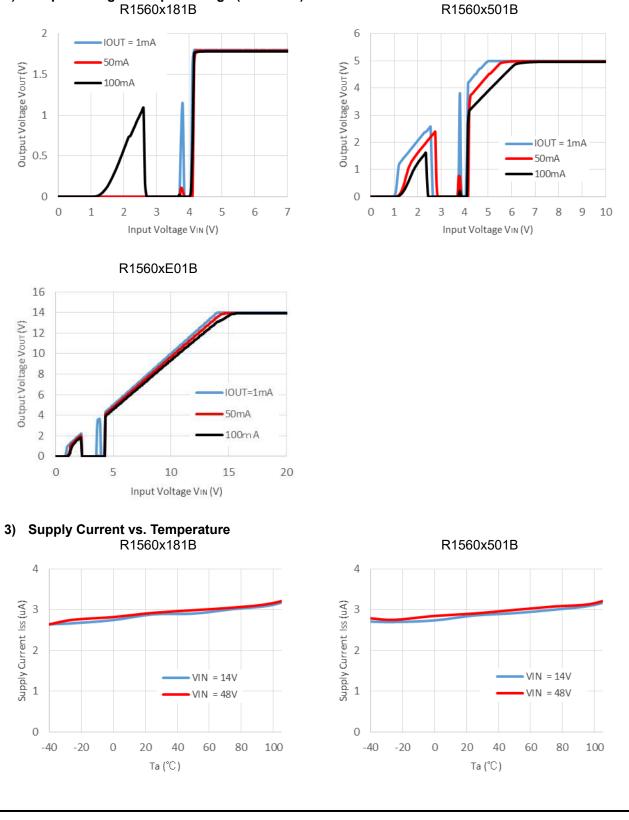








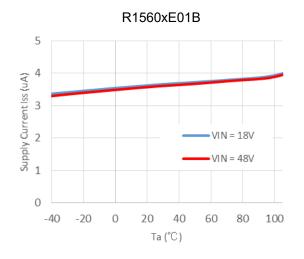
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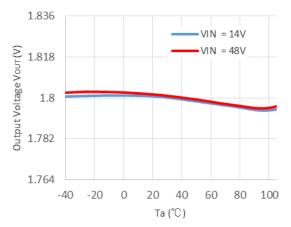
2) Output Voltage vs. Input Voltage (Ta = 25°C) R1560x181B

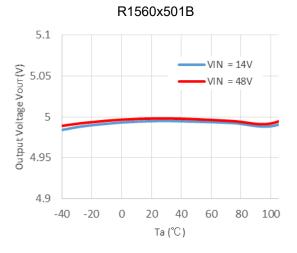
<u>R1560x</u>

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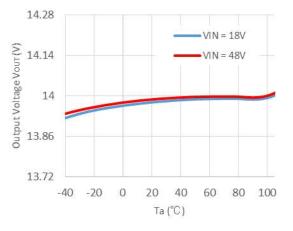




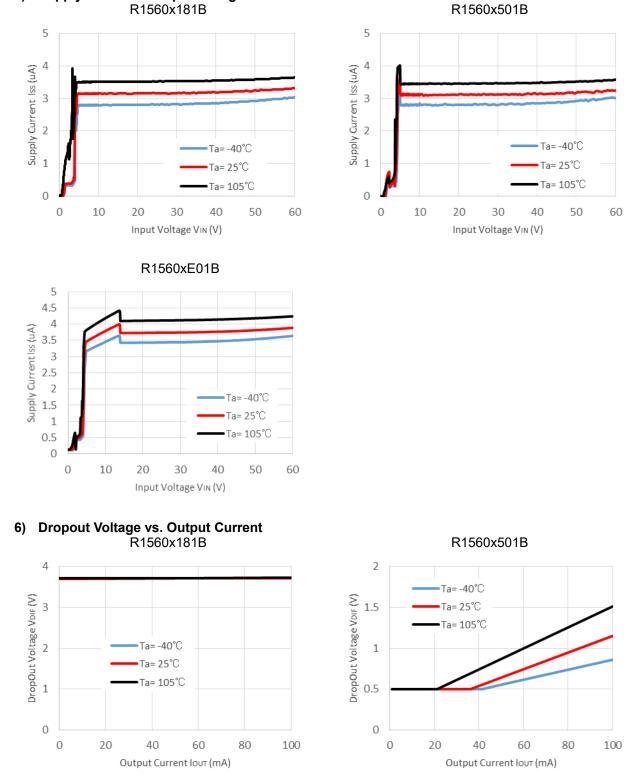






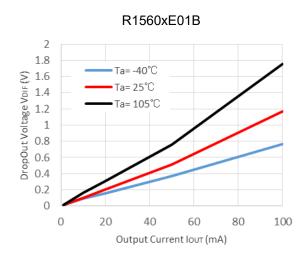


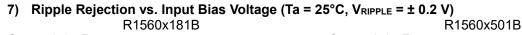
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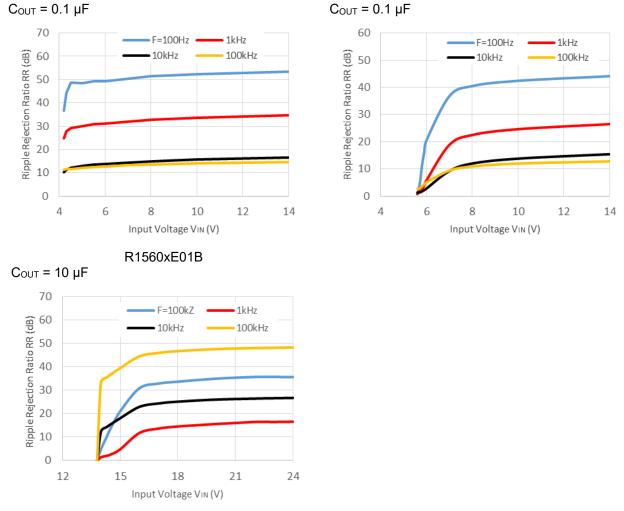


5) Supply Current vs. Input Voltage

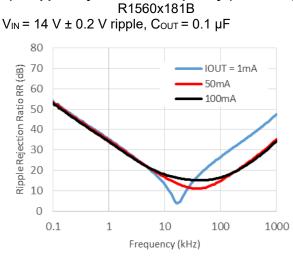
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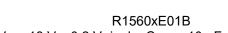


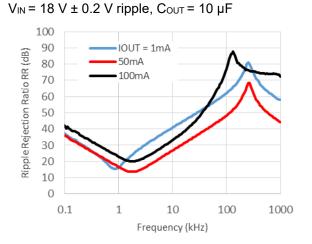


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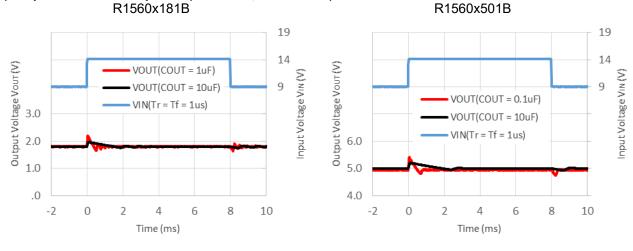


8) Ripple Rejection vs. Frequency (Ta = 25°C)







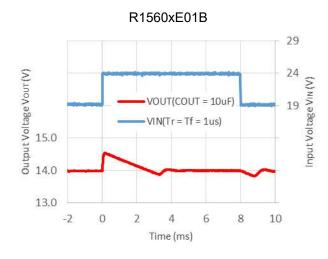


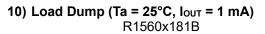
R1560x501B V_{IN} = 14 V ± 0.2 V ripple, C_{OUT} = 0.1 μ F 80 IOUT = 1mA 70 Ripple Rejection Ratio RR (dB) 50mA 60 100mA 50 40 30 20 10 0 0.1 1 10 1000 100 Frequency (kHz)

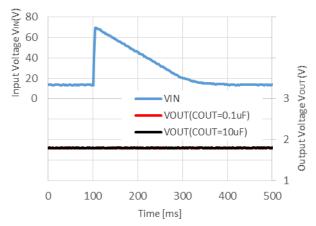
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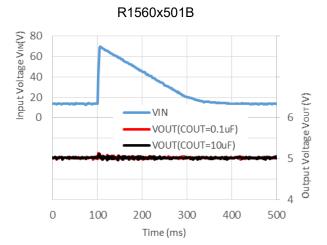
Nisshinbo Micro Devices Inc.

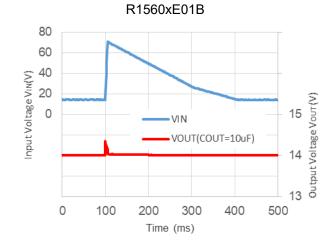
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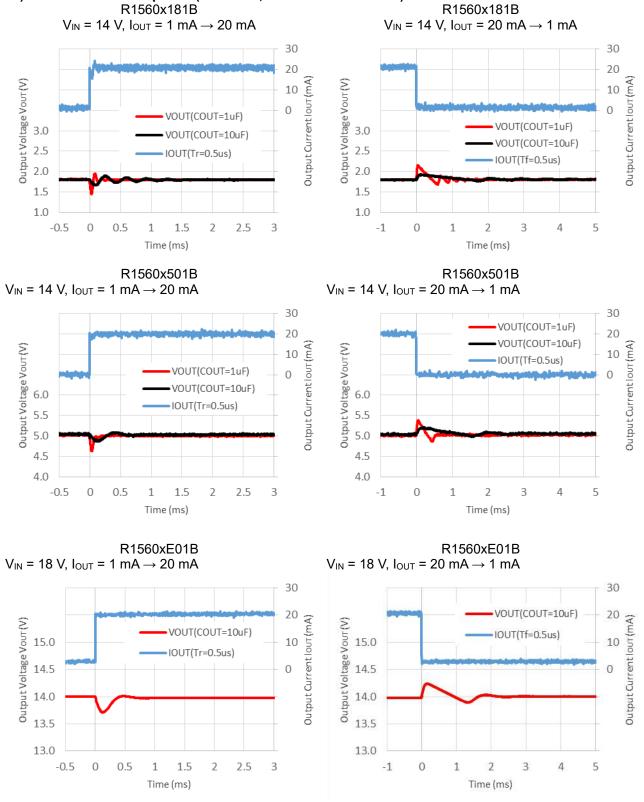






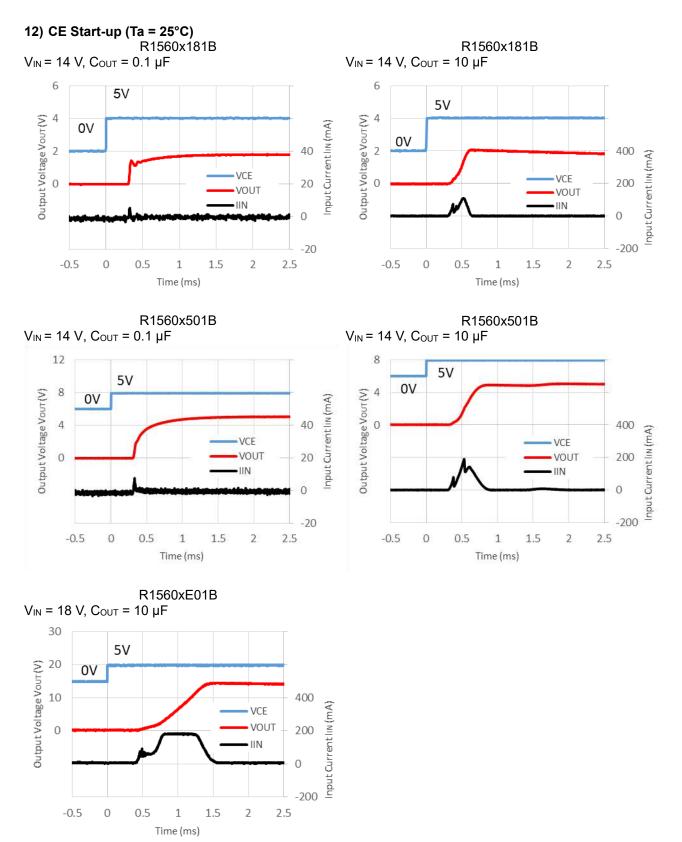


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11) Load Transient Response (Ta = 25°C, Iout = 1 mA ↔ 20 mA)

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POWER DISSIPATION

HSOP-6J

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 28 pcs

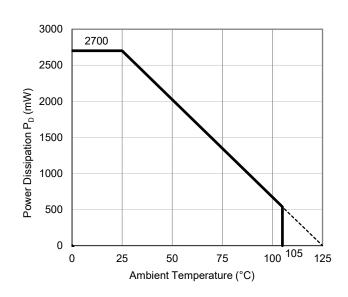
Measurement Conditions

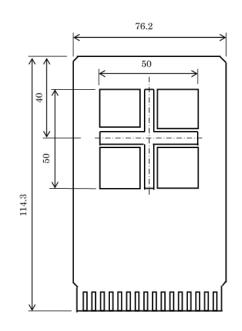
Measurement Result

(Ta = 25°C, Tjmax = 125°C) Item **Measurement Result Power Dissipation** 2700 mW θja = 37°C/W Thermal Resistance (θja) Thermal Characterization Parameter (wjt) $\psi jt = 7^{\circ}C/W$

θja: Junction-to-Ambient Thermal Resistance

wit: Junction-to-Top Thermal Characterization Parameter





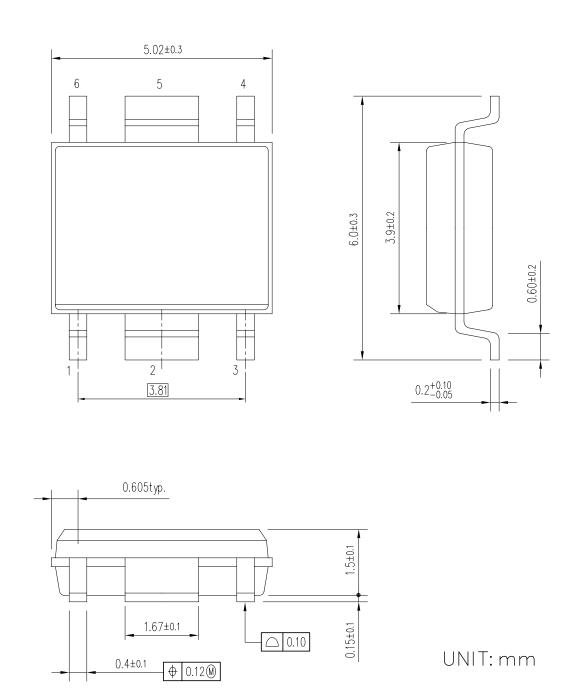
Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

PACKAGE DIMENSIONS

HSOP-6J

Ver. A



HSOP-6J Package Dimensions

Nisshinbo Micro Devices Inc.

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POWER DISSIPATION

TO-252-5

 $(Ta = 25^{\circ}C, Tjmax = 125^{\circ}C)$

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 21 pcs

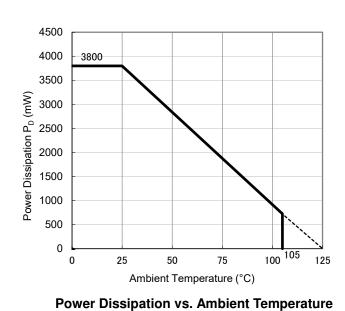
Measurement Conditions

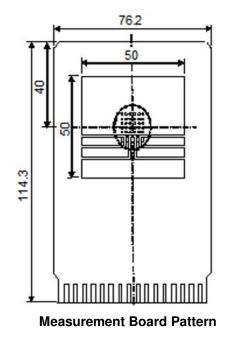
Measurement Result

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Item	Measurement Result
Power Dissipation	3800 mW
Thermal Resistance (θja)	θja = 26°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 7°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

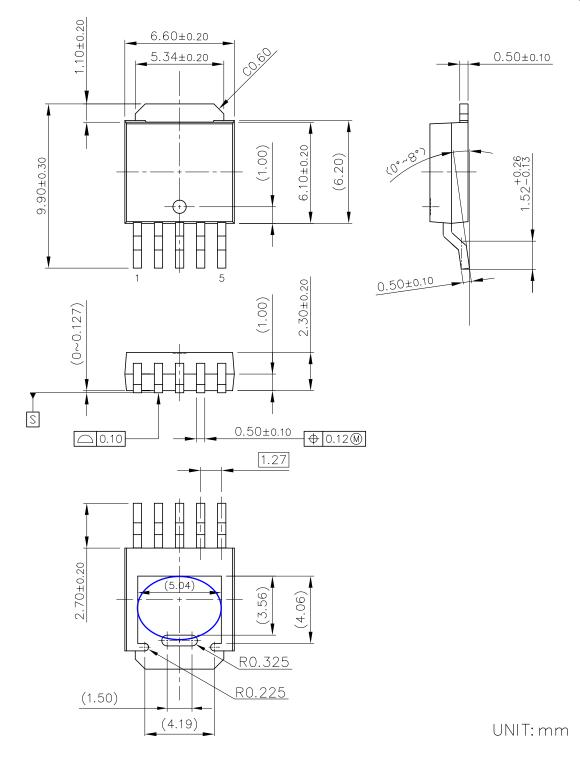




PACKAGE DIMENSIONS

TO-252-5-P2

Ver. A



TO-252-5-P2 Package Dimensions

^{*} The tab on the bottom of the package shown by blue circle is a substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

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